

Online CEBR Concerns and Suggestion

APQP Monitoring System

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ce

CUSTOMER DETAILS

GENERAL REQUIREMENTS

TECHNICAL DATA

QUALITY CONTROLS

REFERENCE DOCS

TECHNICAL DATA

Please fill in the following details

Die Details:  
Please provide the following:

☒ Silicon

☐ Silicon Carbide

☐ GaN

☐ Others:

Die back metal composition:

Die top metal composition:

Wafer Diameter:  
N/A

Soldering Materials:  
Choose one...

Wire Type:

Leadfinish:  
Pure/ Matte Trimplate

Bond pad metal thickness:

Wafer Thickness:

Wire Sizes:

Parametric Test:  
Yes

\*Please provide reference test specnumber:

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Suggestion: Add an option for Die Size and thickness for dies arriving in waffle pack or dies pre-sawn.

Back

CUSTOMER DETAILS

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GENERAL REQUIREMENTS

Please fill in the following details

New Product/Packaging:  
YES

Select Package Type:  
Discrete Product

Select Package:  
TO247

Purpose:  
--Choose One--  
--Choose One--  
Concept  
Design/Developmental Only  
Production  
Prototype/Engg Sample Only  
Product Transfer  
Characterization Only  
Subcon Transfer  
Qualification  
Choose one...

Application:  
--Choose One--

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Suggestion: Add a Costing Option.

☐ PRE-MARK PLATE

☐ 100%

☐ MARKING

☒ TOP

☐ SIDE

☐ BOTTOM

INK TYPE:

LAY-OUT:

Suggestion: Remove Ink type and Add Option for Lasermark or Sticker Label

16

PACK

☒ TPC Std.

☐ Customer Std.

+

×

Mtl Type 1:

SHIELDING BAG: TPC.IS06006

×

Mtl Type 2:

TRACEABILITY LABEL: TPC.IS10027

×

Mtl Type 3:

MASTER BOX C : TPC.IS01004

×

Mtl Type 4:

BAG A/S: TPC.IS06001

×

Mtl Type 5:

SHIPPING LABEL: TPC.IS10041

OTHER REQUIREMENTS:

Suggestion: Add a description box that automatically fill up if the Stock Number is entered.

☐ MARKING

☐ TOP

☐ SIDE

☐ BOTTOM

INK TYPE:

LAY-OUT:

☐ HEAT SOAK

☒ 100%

☐ Sampling

9

TEMP CYCLE

☒ 100%

☐ Sampling

10

CENTRIFUGE

☒ 100%

☐ Sampling

Concern: Unable to unselect choices.

CEBR#	DEVICE	CEBR TYPE	TOTAL RUN	STATUS	DATE CREATED	
CEBR007-01	P/N 2N2971	New Package	1	DRAFT	2023-11-09 17:02:21	 

INFO

CUSTOMER INFORMATION

PACKAGE INFORMATION

PROCESS

REFERENCE DOCUMENTS

WAFER SAW

+

DIE PART#:

DIE TYPE 1:

QTY

DIE SIZE:

DIE THICKNESS:

WAFER SIZE:

DIE PART#:

DIE TYPE 2:

QTY

DIE SIZE:

DIE THICKNESS:

WAFER SIZE:

DIE PLATE

MANUAL

VIKING

1

2ND OPT INSP.

MILITARY

100%

COMMERCIAL

Sampling

Concern: Updating CEBR reset all filled Info's

APQP Monitoring System

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CUSTOMER DETAILSGENERAL REQUIREMENTSTECHNICAL DATAQUALITY CONTROLSREFERENCE DOCS

REFERENCE DOCUMENTS

Tick the checkbox for available documents

☒ Assembly Buildsheet  
[Choose Files](#) BID 2N3971.pdf

☒ Test Data Sheets  
[Choose Files](#) Die Technical data sheet.pdf

☐ Regulatory Requirements  
[Choose Files](#) No file chosen

☒ Package Marking Docs  
[Choose Files](#) BID 2N3971.pdf

☐ Statutory Requirements  
[Choose Files](#) No file chosen

☒ Process Requirements  
[Choose Files](#) Assembly Checklist.pdf

SPECIAL REQUIREMENTS/ INSTRUCTIONS

Process Requirement:  
Assemble per Military STD process  
1) Manual Die attach - Silver Epoxy (Ablestik-B4-1 LM584)  
2) Wire Bond - Aluminum - 125 mils  
3) Marking - Laser Marking  
4) Build 1000 units. Store any remaining dies in controlled environment.  
5) PQ Qty should be the start Qty at Die attach  
Others:  
a) All leads must be straight open. Use original carrier trays in shipping finished parts.  
b) Enclose all travelers, Bond Pull, Die Shear monitor data and C of C when returning finished parts to customer  
c) Any reject Die or any material used for setup must be returned to customer after completion of build  
NOTE:  
a) Certificate of Conformance required after assembly  
b) The entire lot must have the same date code (Shaded same work week)

Oops, something is missing!

Please check all required field.

OK

Previous

Submit

**Suggestion: Notification shows the part missed.**